



Workshop on

Advances in reliability of power devices

Schedule: Thursday 16.40-18.20

A couple of expert will make a few short statements to the topics listed below. Then the attendees will be asked to comment and to name their special interest. Those topics will then be discussed in more detail. Finally a brief summary will be given.

The workshop is moderated by:

- Eckhard Wolfgang, ECPE Nuremberg
- Mauro Ciappa, ETH Zurich

| Topic | Name | Affiliation |
|--|------------------|-----------------------|
| Reliability testing of smart power devices | Werner Kanert | Infineon |
| Power cycling testing of power modules (Al and Cu bond wires) | Oliver Schilling | Infineon |
| Thermal-mechanical analysis of bonding wires | Bernhard Czerny | University of Vienna |
| Planar interconnects | Ralf Schmitt | Semikron |
| Nondestructive SOA testing | Giovanni Busatto | University of Cassino |
| End-of-life simulations | Mauro Ciappa | ETH Zurich |